



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-06-26
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HDQ7*UF97JC2	A	BO2A	2013-06-26
Amount	UoM	Unit type	ST ECOPACK Grade	
154.10	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3,9,9,9,1,25	16	gull wing	
Comment	SO 16 .15 TO JEDEC MS-012			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 Dec 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HDQ7*UF97JC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.181	mg	supplier	die	Silicon (Si)	7440-21-3		2.131	mg	977075	13829
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.031	mg	14214	201
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.013	mg	5961	84
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.006	mg	2751	39
Leadframe	Copper & its alloys	32.023	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.081	mg	970584	201694
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.731	mg	22827	4744
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.044	mg	1374	286
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.038	mg	1187	247
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.117	mg	3654	759
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.004	mg	125	26
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	125	26
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	125	26
Soft solder	Solder	0.74	mg	supplier	solder	Silver (Ag)	7440-22-4		0.673	mg	909459	4367
Soft solder				supplier	solder	acrylate	Proprietary		0.037	mg	50000	240
Soft solder				supplier	solder	Methacrylate	Proprietary		0.03	mg	40541	195
Bonding wire	Other inorganic materials	0.122	mg	supplier	wire	Copper (Cu)	7440-50-8		0.122	mg	1000000	792
encapsulation	Other Organic Materials	119.034	mg	supplier	mold compound	Epoxy Resin	Proprietary		8.927	mg	74995	57930
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		5.952	mg	50003	38624
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		103.083	mg	865996	668936
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.595	mg	4999	3861
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.477	mg	4007	3095